

TECHNICAL DATA SHEET

EU-Directive 2002/95/EG (RoHS)

Electrical and Electronic Equipment Act (ElektroG)

After June 2006 the EU-Directive 2002/95/EG as well as the Electrical and Electronic Equipment Act will be put to effect. These directives restrict the use of lead, mercury, cadmium, hexavalent chrome, polybrominated Biphenyls (PBB) and polybrominated Diphenylethers (PBDE) for any new electronic device brought to market.

We will also adapt to this new situation. Due to the fact that we are not a manufacturer of electronic devices in the sense of the RoHS and the ElektroG, we can't confirm compliance to these directives.

The materials/alloys listed on this data sheet contain the following concentrations of critical substances according to the RoHS resp. to the ElektroG (Rev. Nov. 2005):

material	Pb max. concentration acc. to EU-Directive 1000 ppm	Hg max. concentration acc. to EU-Directive 1000 ppm	Cd max. concentration acc. to EU-Directive 100 ppm	Cr ⁶⁺ max. concentration acc. to EU-Directive 1000 ppm
copper (Cu-ETP, Cu-PHC, Cu-OF)	≤ 5 ppm	< 1 ppm	< 1 ppm	0 ppm
copper alloy (CuZn0,5)	3 ppm	< 1 ppm	1 ppm	0 ppm
brass (CuZn10, 12, 15, 30)	≤ 500 ppm	≤ 1 ppm	≤ 100 ppm	0 ppm
brass (CuZn37)	≤ 1000 ppm	≤ 1 ppm	≤ 100 ppm	0 ppm
bronze (CuSn6)	≤ 500 ppm	≤ 1 ppm	≤ 100 ppm	0 ppm
copper nickel alloy (CuNi44)	0 ppm	0 ppm	0 ppm	0 ppm
nickel (Ni99,6)	0 ppm	0 ppm	0 ppm	0 ppm
german silver (CuNi18Zn20)	< 50 ppm	≤ 1 ppm	0 ppm	0 ppm
silver (Ag 99,99)	< 5 ppm	0 ppm	< 5 ppm	0 ppm
copper, tin clad with pure tin on one side (4% plating)	< 250 ppm	≤ 1 ppm	< 2 ppm	0 ppm
copper, tin clad with pure tin on both sides (4% plating/side)	< 500 ppm	< 1 ppm	< 2 ppm	0 ppm

The materials/alloys listed on this datasheet do contain neither polybrominated Biphenyls (PBB) nor polybrominated Diphenylethers (PBDE).

All data have been obtained with great care and to the best of our knowledge. A guarantee in the legal sense is not implied. The contents are subject to change without notice.